



Product Specification

XBLW SN74LVC1G17

Single Schmitt Trigger Buffer

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Description

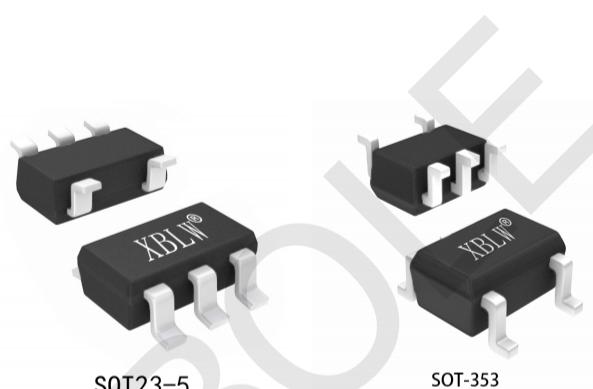
The SN74LVC1G17 provides a buffer function with Schmitt trigger input. It is capable of transforming slowly changing input signals into sharply defined outputs.

The input can be driven from either 3.3V or 5V devices.

This feature allows the use of this device in a mixed 3.3V and 5V environment.

Features

- Wide supply voltage range from 1.65V to 5.5V
- $\pm 24\text{mA}$ output drive ($V_{CC}=3.0\text{V}$)
- CMOS low power consumption
- Direct interface with TTL levels
- Unlimited rise and fall times
- Input accepts voltages up to 5V
- Specified from -40°C to $+125^{\circ}\text{C}$
- Packaging information: SOT-23-5/SOT-353



Applications

- Wireless Headset, Keyboard, and Mouse
- Video Analytics: Server
- AV Receiver
- Audio Dock: Portable
- TV: LCD/Digital and High-Definition (HDTV)
- Tablet: Enterprise
- Solid State Drive (SSD): Client and Enterprise
- Power: Telecom/Server AC/DC Supply: Single Controller: Analog and Digital
- Personal Digital Assistant (PDA)
- MP3 Player/Recorder
- Blu-ray Player and Home Theater

Ordering Information

Product Model	Package Type	Marking	Packing	Packing Qty
XBLW SN74LVC1G17T235	SOT-23-5	AFXX	Tape	3000Pcs/Reel
XBLW SN74LVC1G17T353	SOT-353	AFXX	Tape	3000Pcs/Reel

Block Diagram

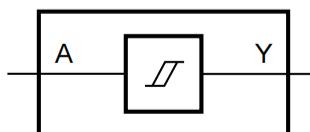


Figure 1. Logic symbol

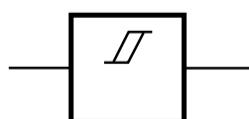


Figure 2. IEC logic symbol

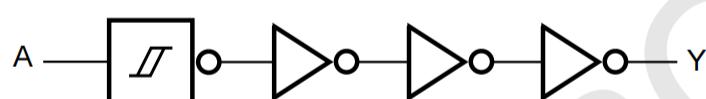
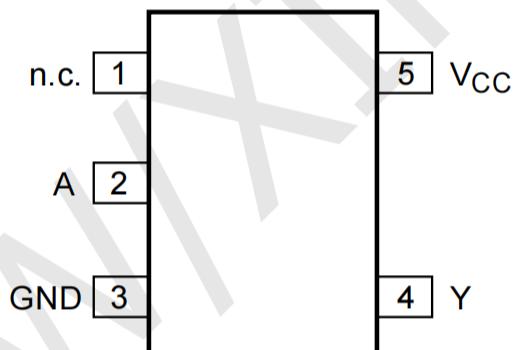


Figure 3. Logic diagram

Pin Configurations



Pin Description

Pin No.	Pin Name	Description
1	n.c.	Not Connected
2	A	Data Input
3	GND	Ground (0V)
4	Y	Data Output
5	Vcc	Supply Voltage

Function Table

Input	Output
A	Y
L	L
H	H

Note: H=HIGH voltage level; L=LOW voltage level.

Electrical Parameter

Absolute Maximum Ratings

(Voltages are referenced to GND (ground = 0V), unless otherwise specified.)

Parameter	Symbol	Conditions	Min.	Max.	Unit
supply voltage	V _{CC}	-	-0.5	+6.5	V
input voltage	V _I	-	-0.5	+6.5	V
output voltage	V _O	Active mode	-0.5	V _{CC} +0.5	V
		Power-down mode; V _{CC} =0V	-0.5	+6.5	V
input clamping current	I _{IK}	V _I < 0V	-50	-	mA
output clamping current	I _{OK}	V _O > V _{CC} or V _O < 0V	-	±50	mA
output current	I _O	V _O =0V to V _{CC}	-	±50	mA
supply current	I _{CC}	-	-	+100	mA
ground current	I _{GND}	-	-100	-	mA
storage temperature	T _{STG}	-	-65	+150	°C
total power dissipation	P _{TOT}	-	-	250	mW
soldering temperature	T _L	10s	260	260	°C

Recommended Operating Conditions

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
supply voltage	V _{CC}	-	1.65	-	5.5	V
input voltage	V _I	-	0	-	5.5	V
output voltage	V _O	Active mode	0	-	V _{CC}	V
		Power-down mode; V _{CC} =0V	0	-	5.5	V
ambient temperature	T _{AMB}	-	-40	-	+125	°C

ESD Ratings

Parameter	Defintion		Value	Unit
V _(ESD)	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001, all pins ⁽¹⁾	±2000	V
		Charged device model (CDM), per JEDEC specification JESD22-C101, all pins ⁽²⁾	±1000	

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

Electrical Characteristics

DC Characteristics 1

($T_{amb} = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$, voltages are referenced to GND (ground = 0V), unless otherwise specified.)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit	
HIGH-level output voltage	V_{OH}	$V_I = V_{T+}$ or V_{T-}	$I_o = -100\mu\text{A}; V_{CC} = 1.65\text{V to } 5.5\text{V}$	$V_{CC} - 0.1$	-	-	V
			$I_o = 4\text{mA}; V_{CC} = 1.65\text{V}$	1.2	-	-	V
			$I_o = -8\text{mA}; V_{CC} = 2.3\text{V}$	1.9	-	-	V
			$I_o = 12\text{mA}; V_{CC} = 2.7\text{V}$	2.2	-	-	V
			$I_o = 24\text{mA}; V_{CC} = 3.0\text{V}$	2.3	-	-	V
			$I_o = 32\text{mA}; V_{CC} = 4.5\text{V}$	3.8	-	-	V
LOW-level output voltage	V_{OL}	$V_I = V_{T+}$ or V_{T-}	$I_o = 100\mu\text{A}; V_{CC} = 1.65\text{V to } 5.5\text{V}$	-	-	0.10	V
			$I_o = 4\text{mA}; V_{CC} = 1.65\text{V}$	-	-	0.45	V
			$I_o = 8\text{mA}; V_{CC} = 2.3\text{V}$	-	-	0.30	V
			$I_o = 12\text{mA}; V_{CC} = 2.7\text{V}$	-	-	0.40	V
			$I_o = 24\text{mA}; V_{CC} = 3.0\text{V}$	-	-	0.55	V
			$I_o = 32\text{mA}; V_{CC} = 4.5\text{V}$	-	-	0.55	V
input leakage current	I_I	$V_I = 5.5\text{V}$ or GND; $V_{CC} = 0\text{V}$ to 5.5V	-	-	± 1	μA	
power-off leakage current	I_{OFF}	V_I or $V_O = 5.5\text{V}$; $V_{CC} = 0\text{V}$	-	-	± 2	μA	
supply current	I_{CC}	$V_I = 5.5\text{V}$ or GND; $I_o = 0\text{A}$; $V_{CC} = 1.65\text{V to } 5.5\text{V}$	-	-	4	μA	
additional supply current	ΔI_{CC}	per pin; $V_I = V_{CC} - 0.6\text{V}$; $I_o = 0\text{A}$; $V_{CC} = 2.3\text{V to } 5.5\text{V}$	-	-	500	μA	
input capacitance	C_I	-	-	5.0	-	pF	

Note: All typical values are measured at maximum V_{CC} and $T_{amb} = 25^{\circ}\text{C}$.

DC Characteristics 2

(T_{amb}=-40°C to +125°C, voltages are referenced to GND (ground = 0V), unless otherwise specified.)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit	
HIGH-level output voltage	V _{OH}	V _I = V _{T+} or V _{T-}	I _O =-100uA; V _{CC} =1.65V to 5.5V	V _{CC} -0.1	-	-	V
			I _O =4mA; V _{CC} =1.65V	0.95	-	-	V
			I _O =8mA; V _{CC} =2.3V	1.7	-	-	V
			I _O =12mA; V _{CC} =2.7V	1.9	-	-	V
			I _O =24mA; V _{CC} =3.0V	2.0	-	-	V
			I _O =32mA; V _{CC} =4.5V	3.4	-	-	V
LOW-level output voltage	V _{OL}	V _I = V _{T+} or V _{T-}	I _O =100uA; V _{CC} =1.65V to 5.5V	-	-	0.10	V
			I _O =4mA; V _{CC} =1.65V	-	-	0.70	V
			I _O =8mA; V _{CC} =2.3V	-	-	0.45	V
			I _O =12mA; V _{CC} =2.7V	-	-	0.60	V
			I _O =24mA; V _{CC} =3.0V	-	-	0.80	V
			I _O =32mA; V _{CC} =4.5V	-	-	0.80	V
input leakage current	I _I	V _I =5.5V or GND; V _{CC} =0V to 5.5V	-	-	±1	uA	
power-off leakage current	I _{OFF}	V _I or V _O =5.5V; V _{CC} =0V	-	-	±2	uA	
supply current	I _{CC}	V _I =5.5V or GND; I _O =0A; V _{CC} =1.65V to 5.5V	-	-	4	uA	
additional supply current	ΔI _{CC}	per pin; V _I =V _{CC} -0.6V; I _O =0A; V _{CC} =2.3V to 5.5V	-	-	500	uA	

AC Characteristics 1

(T_{amb}=-40°C to +85°C, voltages are referenced to GND (ground = 0V), unless otherwise specified.)

Parameter	Symbol	Conditions	Min.	Typ. ^[1]	Max.	Unit	
A to Y propagation delay	t _{PLH}	see Figure 5	V _{CC} =1.65V to 1.95V	-	14	21	ns
			V _{CC} =2.3V to 2.7V	-	10	15	ns
			V _{CC} =2.7V	-	9	13.5	ns
			V _{CC} =3.0V to 3.6V	-	8	12	ns
			V _{CC} =4.5V to 5.5V	-	7	10.5	ns
A to Y propagation delay	t _{PHL}	see Figure 5	V _{CC} =1.65V to 1.95V	-	12.5	18.8	ns
			V _{CC} =2.3V to 2.7V	-	11	16.5	ns
			V _{CC} =2.7V	-	11	16.5	ns
			V _{CC} =3.0V to 3.6V	-	11	16.5	ns
			V _{CC} =4.5V to 5.5V	-	10	15	ns

Note:

[1] Typical values are measured at T_{amb}=25°C and V_{CC}=1.8V, 2.5V, 2.7V, 3.3V and 5.0V respectively.

AC Characteristics 2

(T_{amb}=-40°C to +125°C, voltages are referenced to GND (ground = 0V), unless otherwise specified.)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
A to Y propagation delay	t _{PLH}	V _{CC} =1.65V to 1.95V	-	-	23	ns
		V _{CC} =2.3V to 2.7V	-	-	17	ns
		V _{CC} =2.7V	-	-	15.5	ns
		V _{CC} =3.0V to 3.6V	-	-	14	ns
		V _{CC} =4.5V to 5.5V	-	-	12.5	ns
A to Y propagation delay	t _{PHL}	V _{CC} =1.65V to 1.95V	-	-	20.8	ns
		V _{CC} =2.3V to 2.7V	-	-	18.5	ns
		V _{CC} =2.7V	-	-	18.5	ns
		V _{CC} =3.0V to 3.6V	-	-	18.5	ns
		V _{CC} =4.5V to 5.5V	-	-	17	ns

Transfer Characteristics 1

(T_{amb}=-40°C to +85°C, voltages are referenced to GND (ground = 0V), unless otherwise specified.)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
positive-going threshold voltage	V _{T+}	V _{CC} =1.8V	0.82	1.02	1.2	V
		V _{CC} =2.3V	1.03	1.25	1.45	V
		V _{CC} =3.0V	1.29	1.5	1.71	V
		V _{CC} =4.5V	1.84	2.15	2.41	V
		V _{CC} =5.5V	2.19	2.6	2.91	V
negative-going threshold voltage	V _{T-}	V _{CC} =1.8V	0.45	0.6	0.75	V
		V _{CC} =2.3V	0.64	0.8	0.96	V
		V _{CC} =3.0V	0.86	1.1	1.34	V
		V _{CC} =4.5V	1.35	1.75	2.09	V
		V _{CC} =5.5V	1.61	2.15	2.59	V
hysteresis voltage	V _H	V _{CC} =1.8V	-	0.4	-	V
		V _{CC} =2.3V	-	0.4	-	V
		V _{CC} =3.0V	-	0.42	-	V
		V _{CC} =4.5V	-	0.45	-	V
		V _{CC} =5.5V	-	0.47	-	V

Transfer Characteristics 2

(T_{amb}=-40°C to +125°C, voltages are referenced to GND (ground = 0V), unless otherwise specified.)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
positive-going threshold voltage	V _{T+}	V _{CC} =1.8V	0.79	-	1.2	V
		V _{CC} =2.3V	1.00	-	1.45	V
		V _{CC} =3.0V	1.26	-	1.71	V
		V _{CC} =4.5V	1.81	-	2.41	V
		V _{CC} =5.5V	2.16	-	2.91	V
negative-going threshold voltage	V _{T-}	V _{CC} =1.8V	0.45	-	0.78	V
		V _{CC} =2.3V	0.64	-	0.99	V
		V _{CC} =3.0V	0.86	-	1.37	V
		V _{CC} =4.5V	1.35	-	2.12	V
		V _{CC} =5.5V	1.61	-	2.62	V
hysteresis voltage	V _H	V _{CC} =1.8V	-	0.4	-	V
		V _{CC} =2.3V	-	0.4	-	V
		V _{CC} =3.0V	-	0.42	-	V
		V _{CC} =4.5V	-	0.45	-	V
		V _{CC} =5.5V	-	0.47	-	V

Testing Circuit

AC Testing Circuit

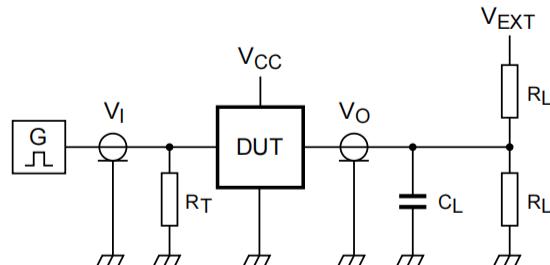


Figure 4. Test circuit for measuring switching times

Definitions for test circuit:

R_L =Load resistance.

C_L =Load capacitance including jig and probe capacitance.

R_T =Termination resistance; should be equal to the output impedance Z_o of the pulse generator.

V_{EXT} =External voltage for measuring switching times.

AC Testing Waveforms

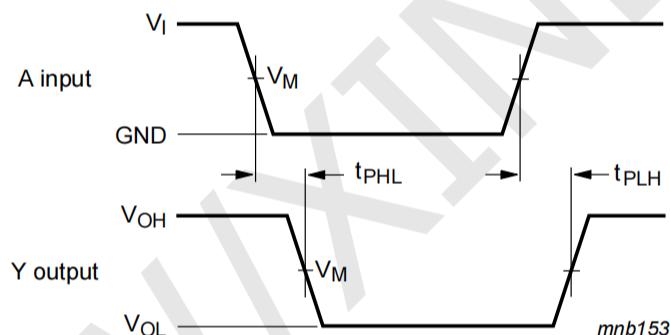


Figure 5. The data input (A) to output (Y) propagation delays

Transfer Characteristics Waveforms

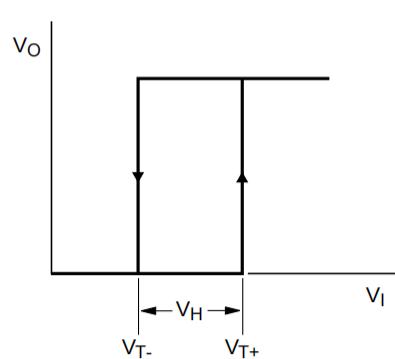


Figure 6. Transfer characteristic

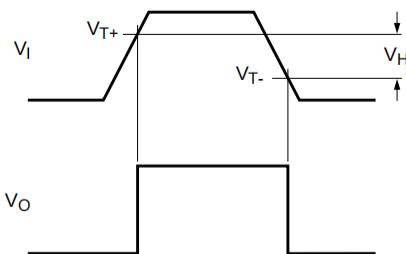


Figure 7. Definition of V_{T+} , V_{T-} and V_H

Measurement Points

Supply voltage	Input	Output
V_{CC}	V_M	V_M
1.65V to 1.95V	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$
2.3V to 2.7V	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$
2.7V	1.5V	1.5V
3.0V to 3.6V	1.5V	1.5V
4.5V to 5.5V	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$

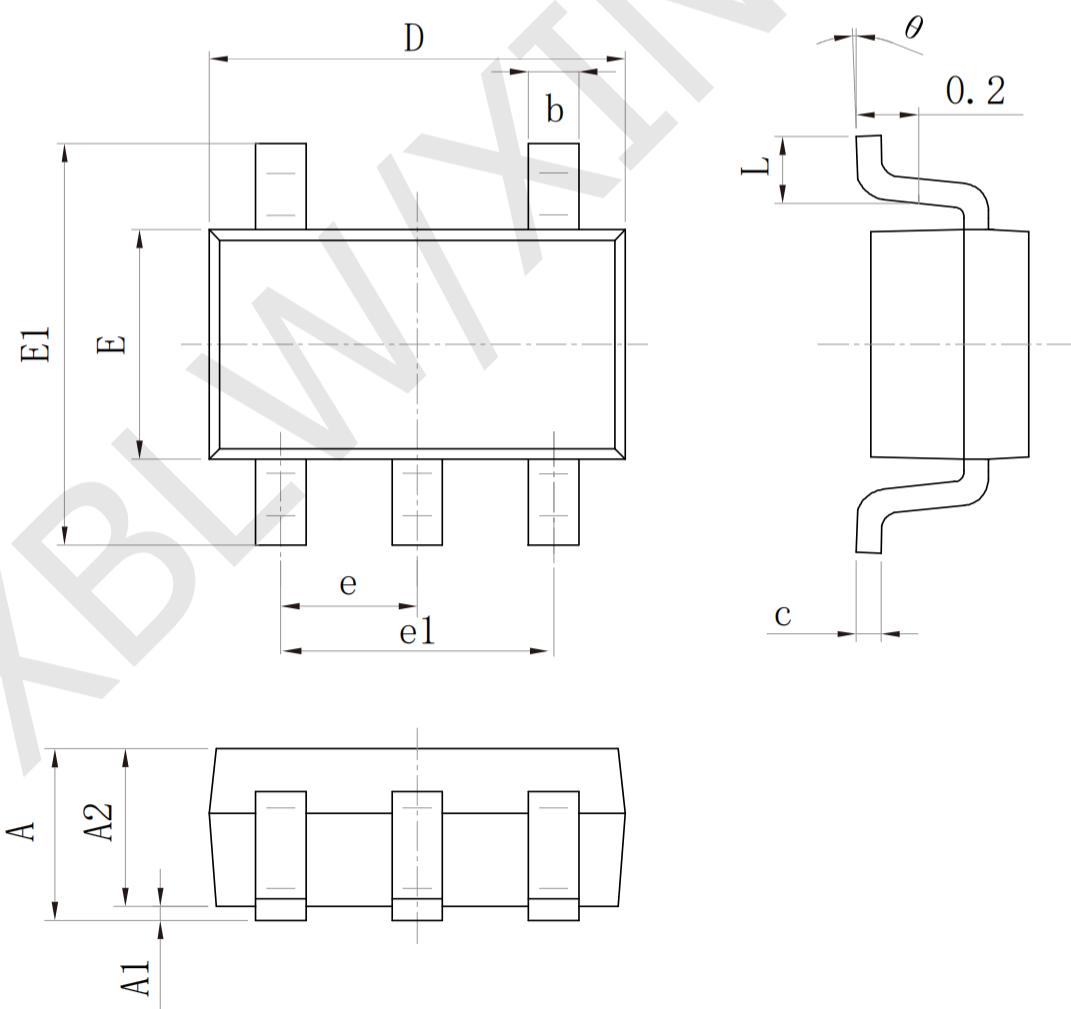
Test Data

Supply voltage	Input		Load		V_{EXT}
V_{CC}	V_I	$t_r = t_f$	C_L	R_L	t_{PLH}, t_{PHL}
1.65V to 1.95V	V_{CC}	$\leq 3\text{ns}$	30pF	1k Ω	open
2.3V to 2.7V	V_{CC}	$\leq 3\text{ns}$	30pF	500 Ω	open
2.7V	2.7V	$\leq 3\text{ns}$	50pF	500 Ω	open
3.0V to 3.6V	2.7V	$\leq 3\text{ns}$	50pF	500 Ω	open
4.5V to 5.5V	V_{CC}	$\leq 3\text{ns}$	50pF	500 Ω	open

Package Information

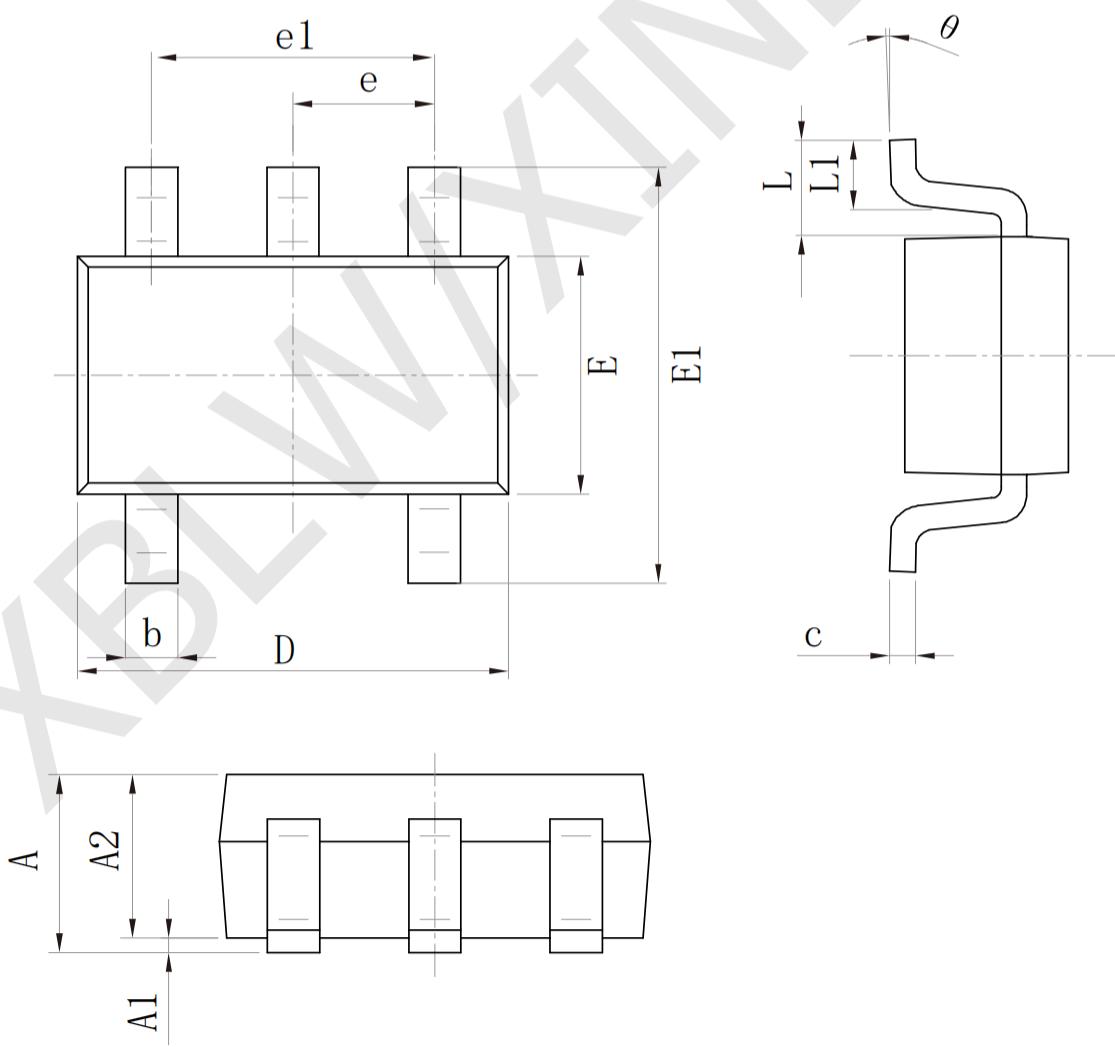
- SOT23-5

SIZE SYMBOL	Dimensions In Millimeters		SIZE SYMBOL	Dimensions In Inches	
	MIN (mm)	MAX (mm)		MIN (in)	MAX (in)
A	1.050	1.250	A	0.041	0.049
A1	0.000	0.100	A1	0.000	0.004
A2	1.050	1.150	A2	0.041	0.045
b	0.300	0.500	b	0.012	0.020
c	0.100	0.200	c	0.004	0.008
D	2.820	3.020	D	0.111	0.119
E	1.500	1.700	E	0.059	0.067
E1	2.650	2.950	E1	0.104	0.116
e	0.95 (BSC)		e	0.037 (BSC)	
e1	1.800	2.000	e1	0.071	0.079
L	0.300	0.600	L	0.012	0.024
θ	0°	8°	θ	0°	8°



- SOT-353

Size Symbol	Dimensions In Millimeters		Size Symbol	Dimensions In Inches	
	Min (mm)	Max (mm)		Min (in)	Max (in)
A	0.900	1.100	A	0.035	0.043
A1	0.000	0.100	A1	0.000	0.004
A2	0.900	1.000	A2	0.035	0.039
b	0.150	0.350	b	0.006	0.014
c	0.080	0.150	C	0.003	0.006
D	2.000	2.200	D	0.079	0.087
E	1.150	1.350	E	0.045	0.053
E1	2.150	2.450	E1	0.085	0.096
e	0.650 (TYP)		e	0.026 (TYP)	
e1	1.200	1.400	e1	0.047	0.055
L	0.525 (REF)		L	0.021 (REF)	
L1	0.260	0.460	L1	0.010	0.018
θ	0°	8°	θ	0°	8°



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